Fan Out Type Wafer Level Package Structure and Method of the Same

ABSTRACT OF THE INVENTION

To pick and place standard dies on a new base for obtaining an appropriate and wider distance between dies than the original distance of dies on a wafer. The package structure has a larger size of balls array than the size of the die by fan out type package. Moreover, the die may be packaged with passive components or other dies with a side by side structure or a stacking structure.

(Fig. 7)